



# Sensor development – State-of-the-art review

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**AMRC Sheffield, UK**

[www.cranfield.ac.uk](http://www.cranfield.ac.uk)

# Overview

- Introduction
- Dimensional metrology tools
- Non-dimensional sensing
- Future requirements





# Surface Engineering and Precision Institute

**We envision a UK manufacturing sector with world abundant *Engineering for life* products for extreme service.**

Advanced Functional Coatings supported by the National High Temperature Surface Engineering Centre, Sol-Gel Centre and Nanotechnology Labs.

Precision Device Manufacturing: Cranfield Nano, specialising in creating new forms of materials for detectors, sensors, biosensors, and actuators,

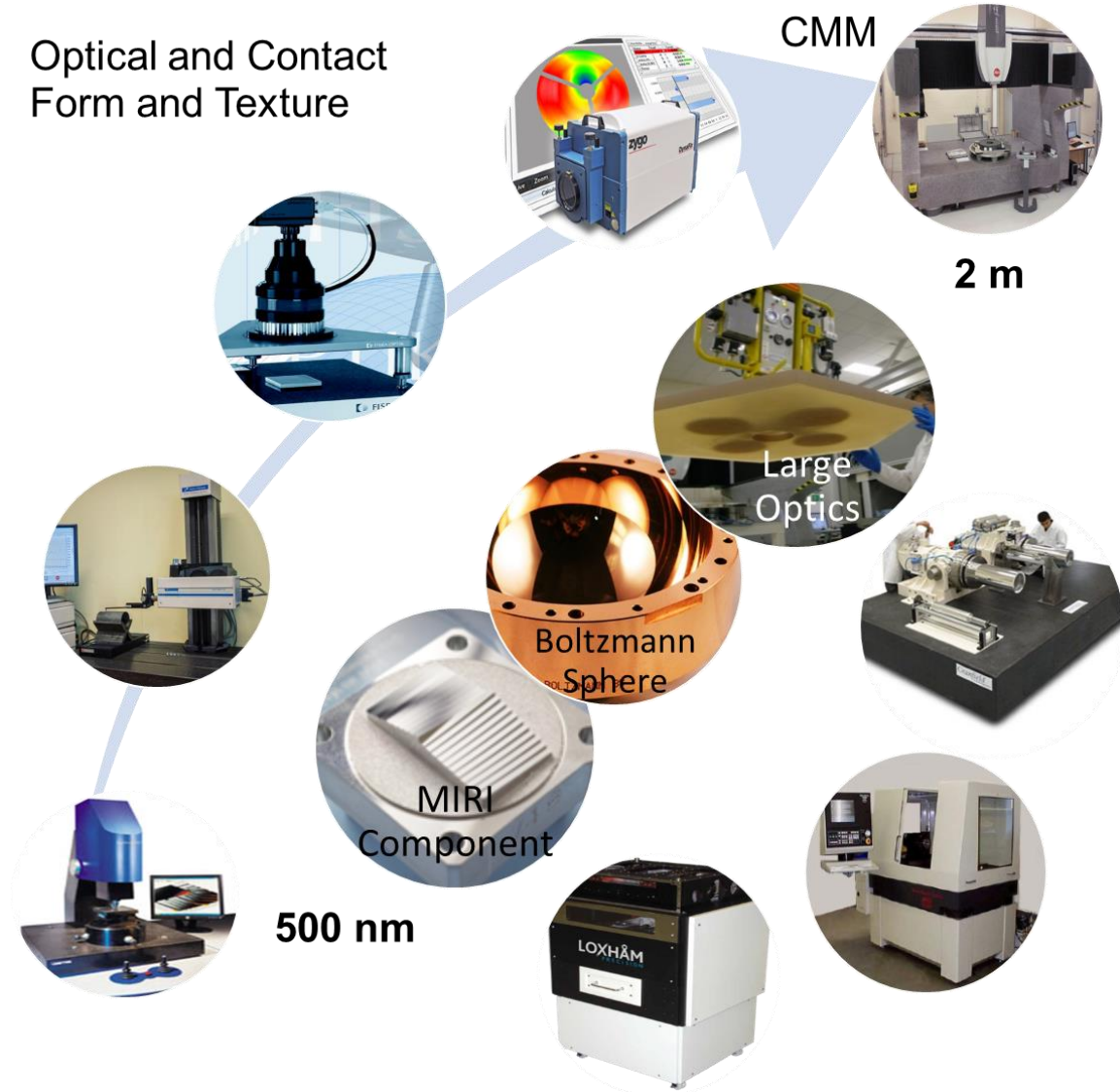
In-Process Metrology: metrology applied as closely as possible to the point of manufacture supported by world-class Precision and ultra precision engineering laboratories



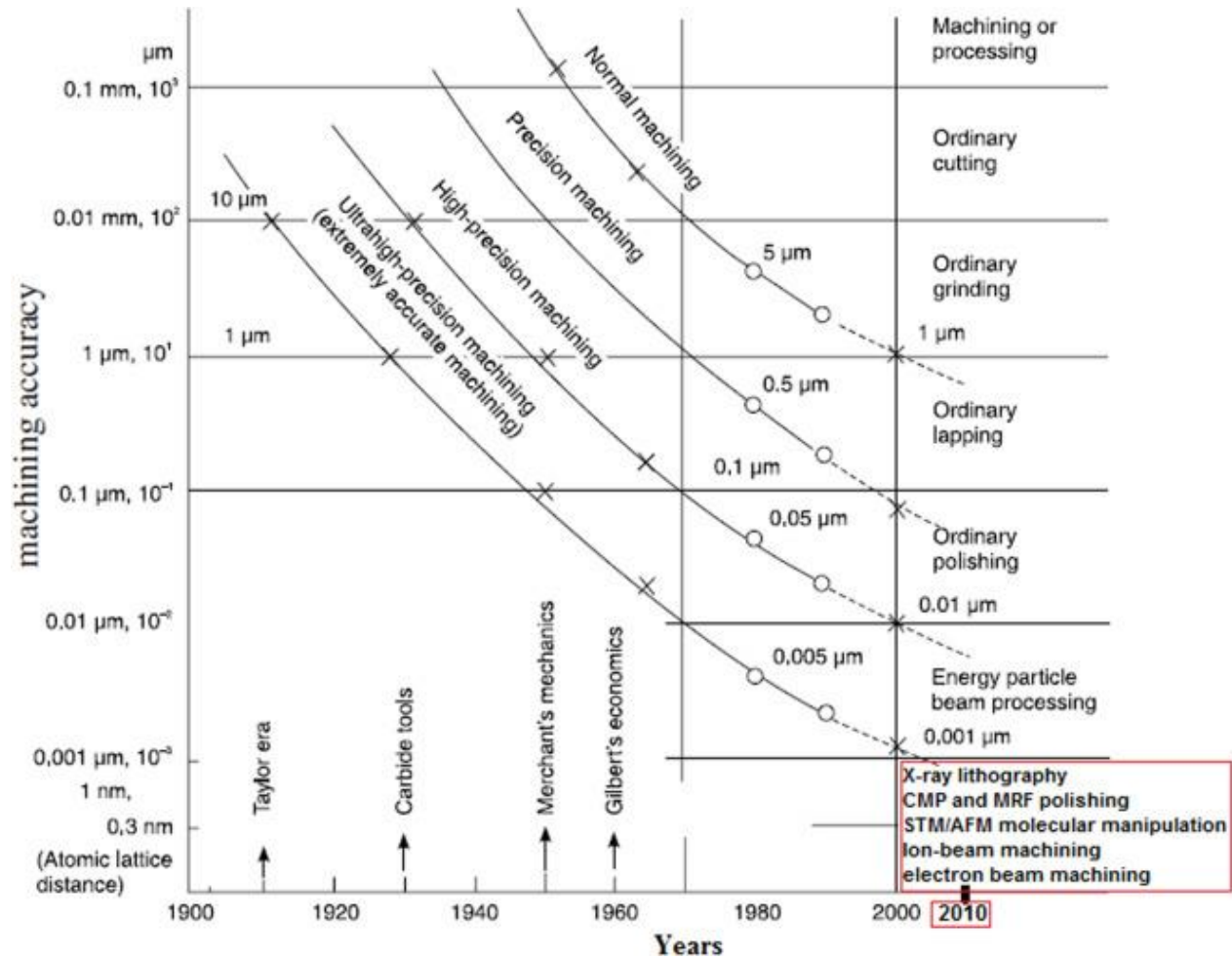


# QA/QC

Optical and Contact  
Form and Texture



# A bit of context – Taniguchi’s chart





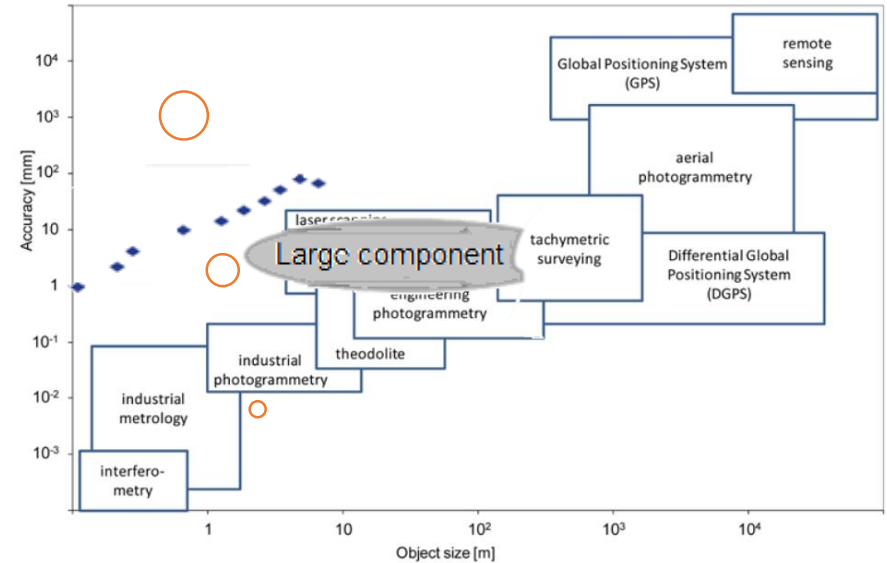
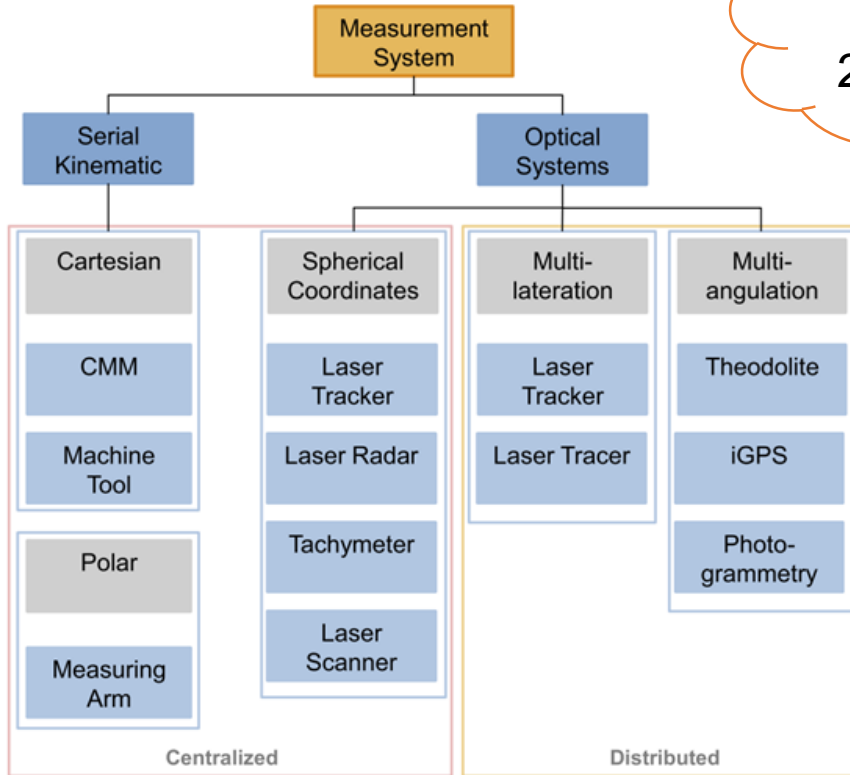
# Achievable surface quality

	nano-machining	micro-machining	macro-machining
size of machined area	$1-10^5 \mu\text{m}^2$	$1-10^5 \text{mm}^2$	$1-10^5 \text{cm}^2$
volume removal in one machining step	from $10^{-3}$ to $10^2 \mu\text{m}^3$	from $10^{-3}$ to $10^2 \text{mm}^3$	from $10^{-3}$ to $10^2 \text{cm}^3$
material removal rate	from $10^{-5}$ to $1 \mu\text{m}^3 \text{s}^{-1}$	from $10^{-5}$ to $1 \text{mm}^3 \text{s}^{-1}$	from $10^{-5}$ to $1 \text{cm}^3 \text{s}^{-1}$
relative figure error	from $10^{-5}$ to $10^{-3}$	from $10^{-7}$ to $10^{-5}$	from $10^{-5}$ to $10^{-3}$
surface roughness ( $S_a$ )	$1-10^2 \text{Å}$	$1-10^2 \text{nm}$	from $10^{-1}$ to $10 \mu\text{m}$

Brinksmeier E and Preuss W (2012) *Philos. Trans. R. Soc. A: Math. Phys. Eng. Sci.* **370** 3973-3992.

# Large-Scale Metrology (LSM)

Challenging applications  
20  $\mu\text{m}$  in 4 m



Schmitt RH *et al.* (2016) CIRP Annals **65** 643-665

Franceschini F *et al.* in *Distributed Large-Scale Dimensional Metrology* Springer (2011)





# Tactile

Available with contact and non-contact probes

Weckenmann A et al.(2004) *CIRP Annals* **53** 657–684

Weckenmann A et al. (2006) *Meas Sci Technol* **17** 504-509

Large CMM-s (5 m)

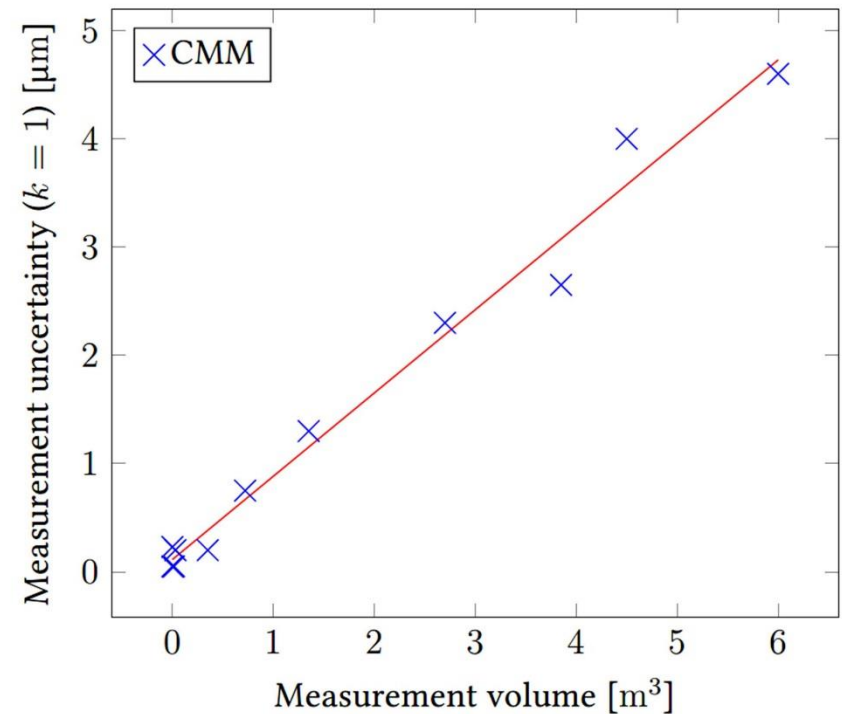
**7  $\mu\text{m}$  + L/250  $\mu\text{m}$**

Schmitt RH et al. (2016) *CIRP Annals* **65** 643-665

Micro CMM-s

**probe errors in excess of 50 nm**

Thalmann R et al. (2016) *Appl. Sci.* **6** 150



Norman J (2019) PhD Thesis





# Optical

## Laser Tracker

Lau K *et al.* (1986) *Prec. Eng.* **8** 3-8

Muralikrishnan B (2016) *Prec. Eng.* **44** 13-28

$$[0.3^2 + (0.4 \times 10^{-3} L)^2]^{1/2} \mu\text{m}$$

Umetsu K (2005) *Meas. Sci. Technol.* **16** 2466-2472

## Laser Tracers

$$0.2 \mu\text{m} + 0.3 \mu\text{m/m} (k=2)$$

Hughes EB *et al.* (2000) *CIRP Annals* **41** 391-394

## FSI (Frequency Scanning Interferometry)

$$40 \mu\text{m in } 10 \text{ m} \times 5 \text{ m} \times 2.5 \text{ m}$$

Dale J *et al.* (2014) *Opt. Exp.* **22** 24869-24893

Other techniques are less accurate:

Coherent laser radars

Laser line scanners

Photogrammetry

Schmitt RH *et al.* (2016) *CIRP Annals* **65** 643-665

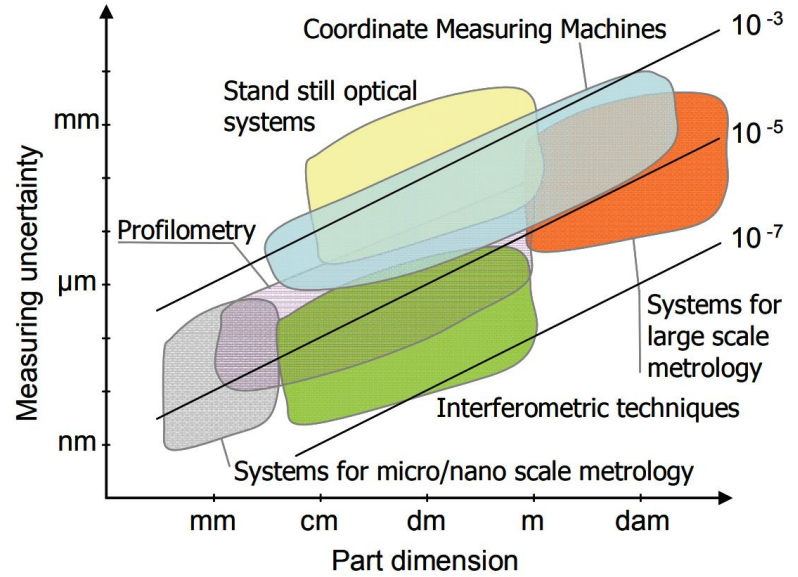
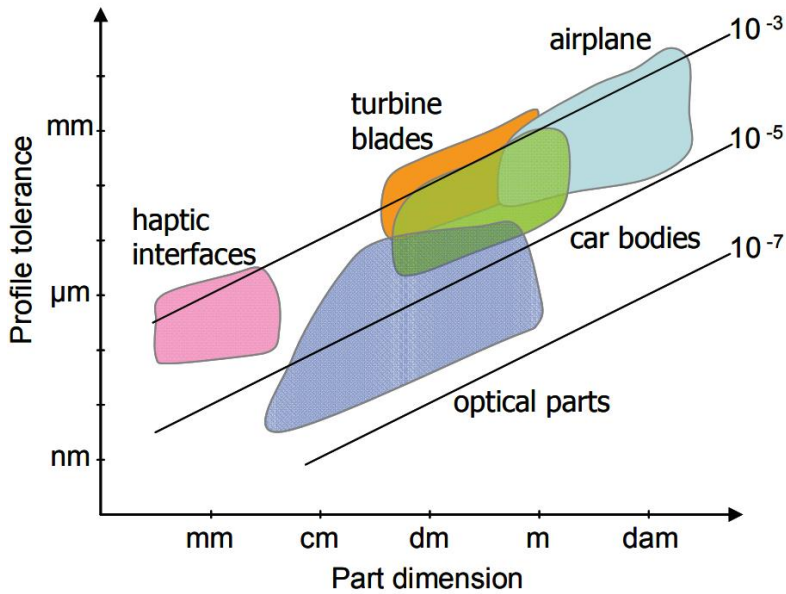
Various form measurement interferometric configurations are able to achieve **sub-nanometre** measurement repeatability.

Wyant JC (2018) *Proc. SPIE* **10749** 107490P

Issues with Lateral Dynamic Range v measurable slope (Loughborough talk)

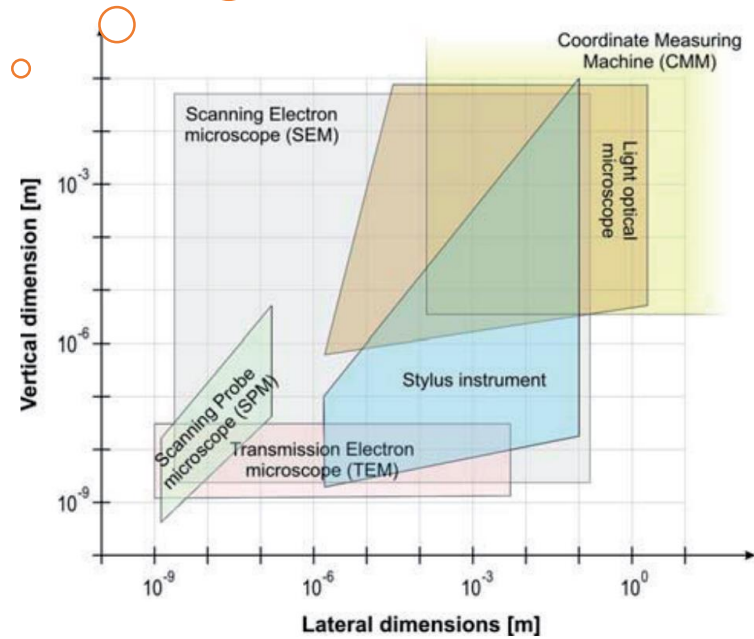
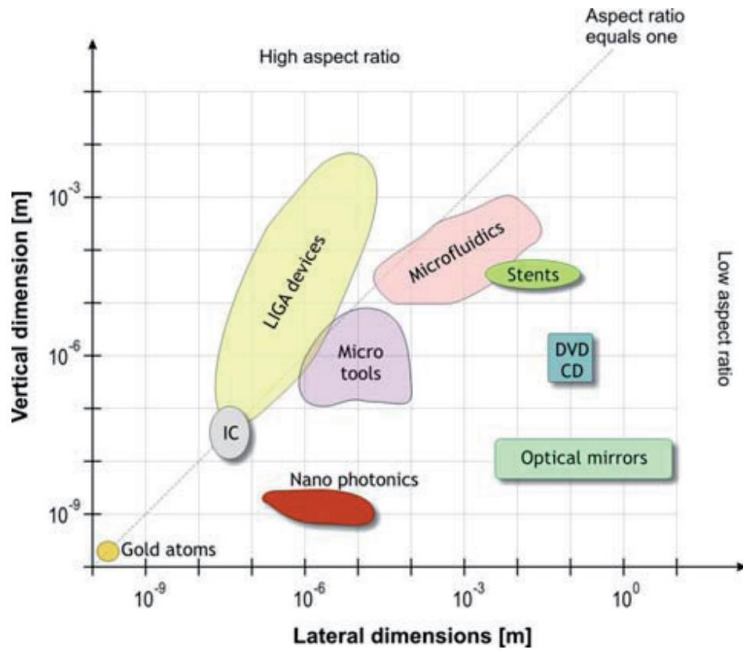
# Medium to small scale

1:5 ratio  
uncertainty  
tolerance difficult to  
achieve



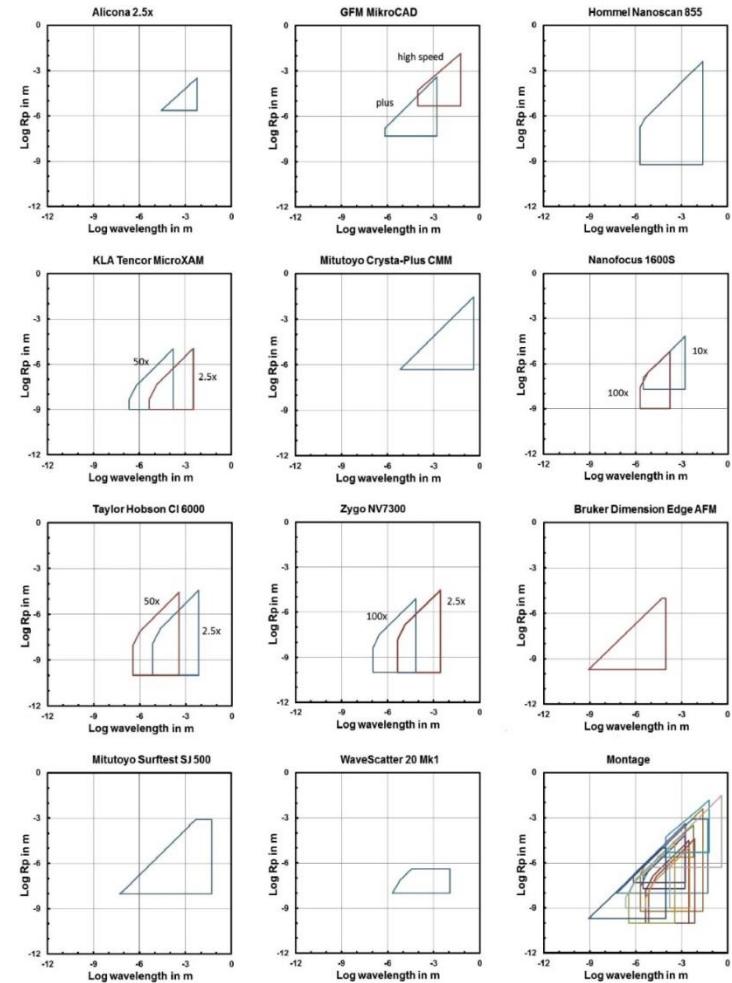
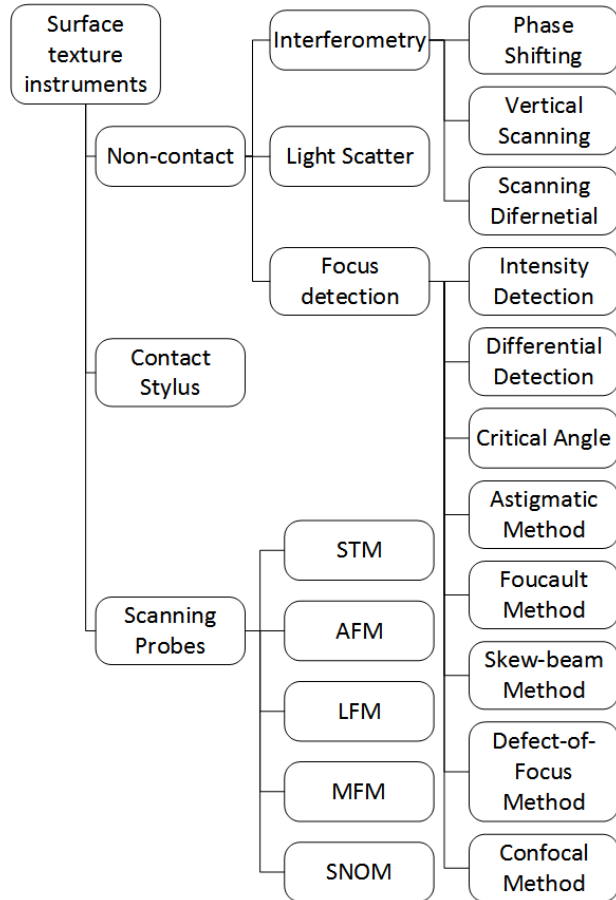
Savio E *et al.* (2007) CIRP Annals **56** 643-665

# Micro and below ...



Hansen HN *et al.* (2006) CIRP Annals **55** 721-743

# Surface texture (ISO25178 standards)

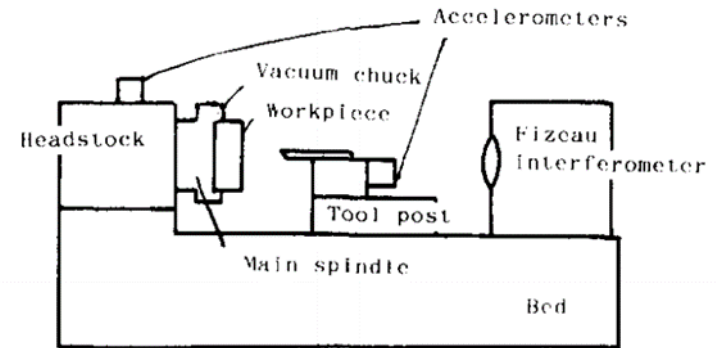


Mostly developed for two reasons:

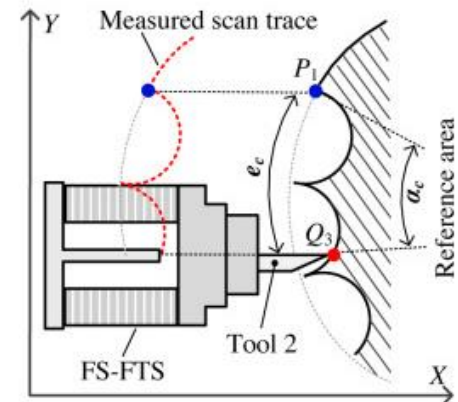
- Tool positioning and alignment
- Error compensation

Added benefits:

- QA/QC
- Process monitoring
- Various interferometric techniques
- Photogrammetry
- Fringe projection
- 3D microscopes (ST)
- Optical and contact probes
- Laser trackers
- AFMs

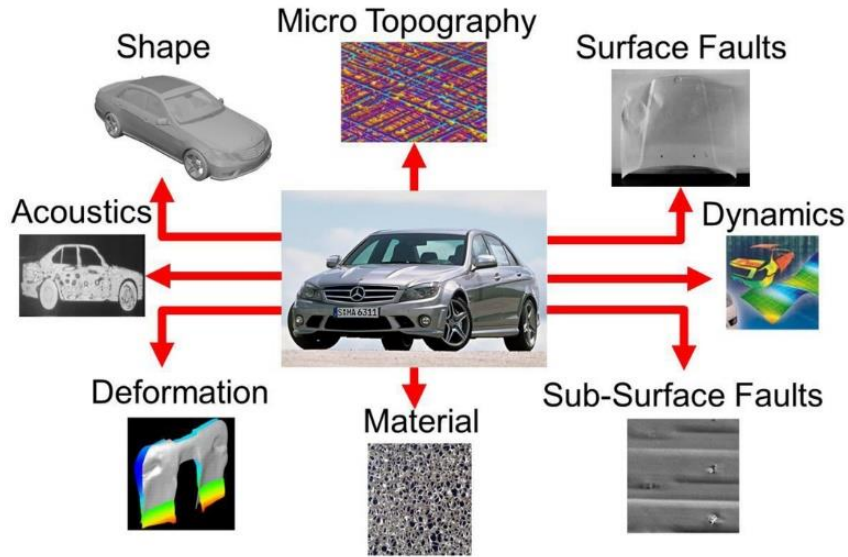


Nomura T et al. (1992) *Prec Eng* **14** 155-159

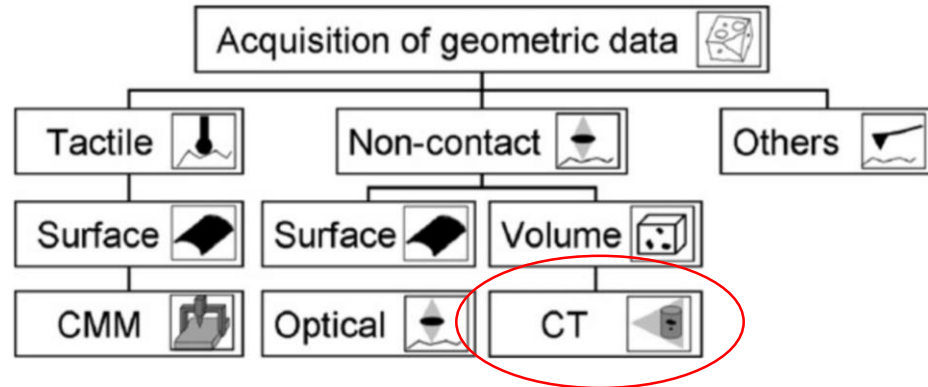


Gao W et al. (2013) *CIRP Annals* **62** 523-526

# Sensors requirements



## Multi-Sensor Data Fusion Geometrical

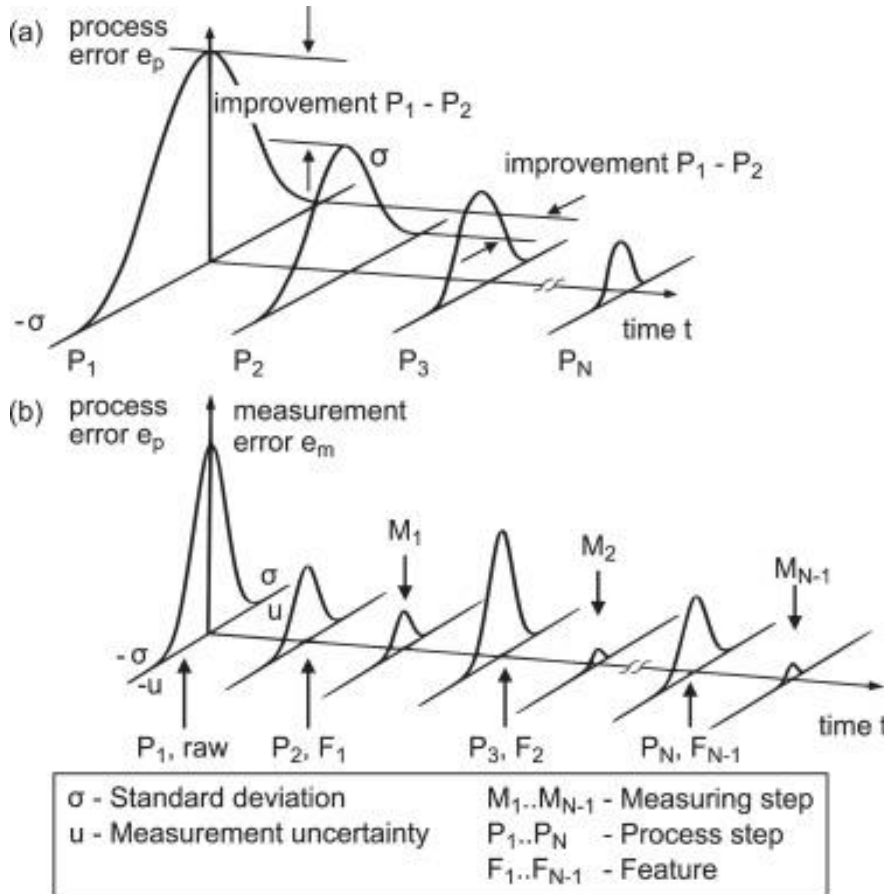


Weckenmann A et al. (2009) *CIRP Ann.* **58** 701-721





# What do we try to achieve and in which context?

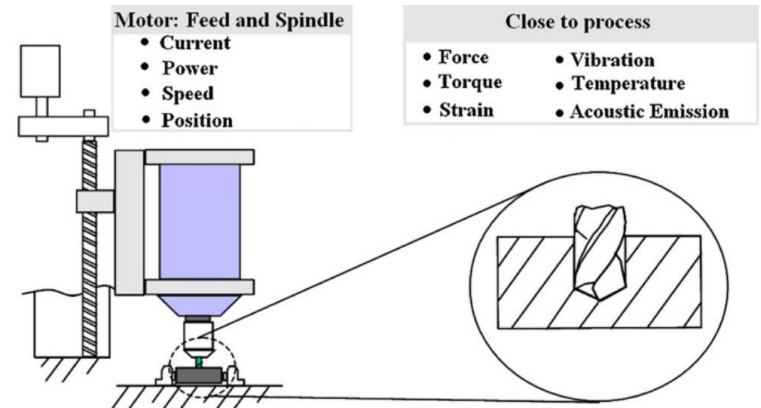
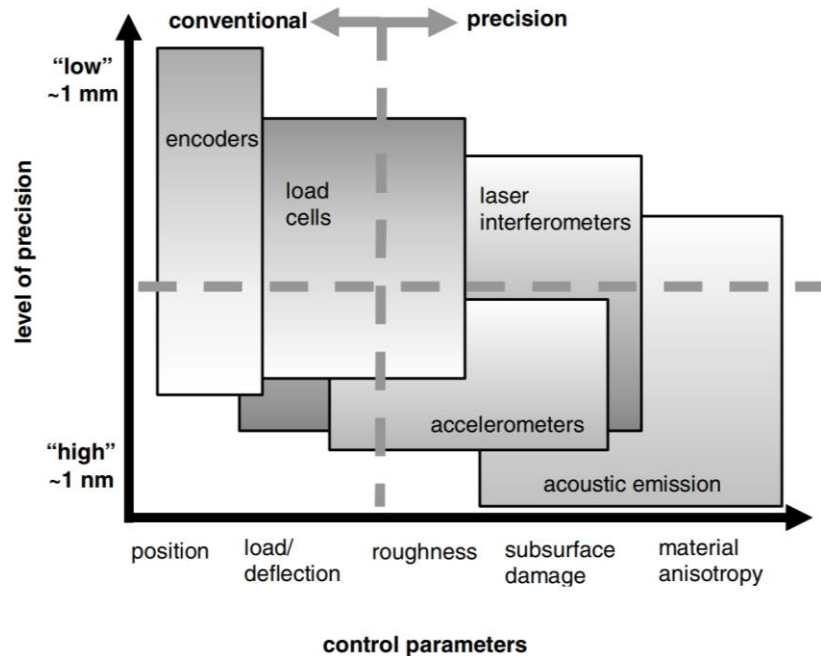


Ulhman E *et al.* (2016) *CIRP Annals* **65** 549-572



# Sensors required for machine tool control

## Sensor application versus level of precision and control parameters



Lee DE *et al.* in *Condition Monitoring and Control for Intelligent Manufacturing* Wang L and Gao RX Springer, London (2006), 33-54

Teti R *et al.* (2010) *CIRP Annals* **59** 717-739

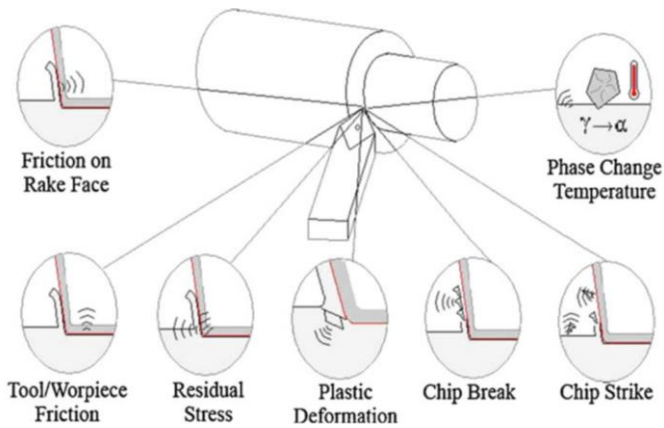


## Displacement sensors

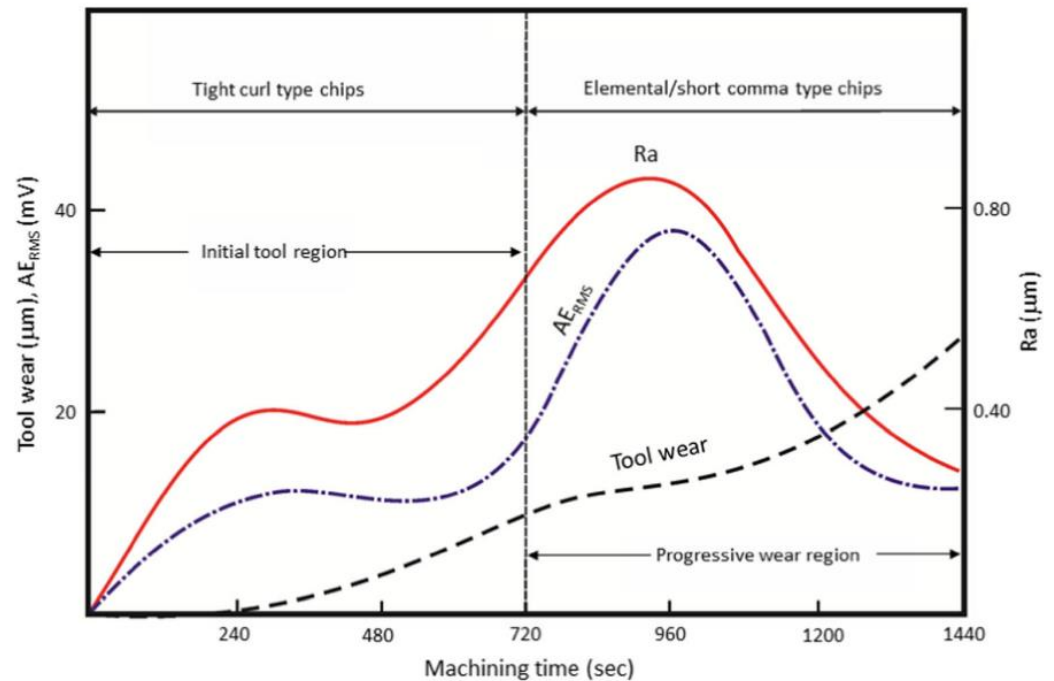
Sensor type	Range	Resolution	Max. BW	Accuracy
Metal foil	10–500 $\mu\text{m}$	23 nm	1–10 kHz	1% FSR
Piezoresistive	1–500 $\mu\text{m}$	0.49 nm	>100 kHz	1% FSR
Capacitive	10 $\mu\text{m}$ to 10 mm	2.4 nm	100 kHz	0.1% FSR
Electrothermal	10 $\mu\text{m}$ to 1 mm	10 nm	10 kHz	1% FSR
Eddy current	100 $\mu\text{m}$ to 80 mm	1 nm	40 kHz	0.1% FSR
LVDT	0.5–500 mm	5 nm	1 kHz	0.25% FSR
Interferometer	Meters	0.49 nm	>100 kHz	1 ppm FSR
Encoder	Meters	6 nm	>100 kHz	5 ppm FSR

Flaming AJ (2010) *Sens Actua A-Phys* **190** 106-126

# Acoustic emission sensors



Teti R *et al.* (2010) *CIRP Annals* **59** 717-739

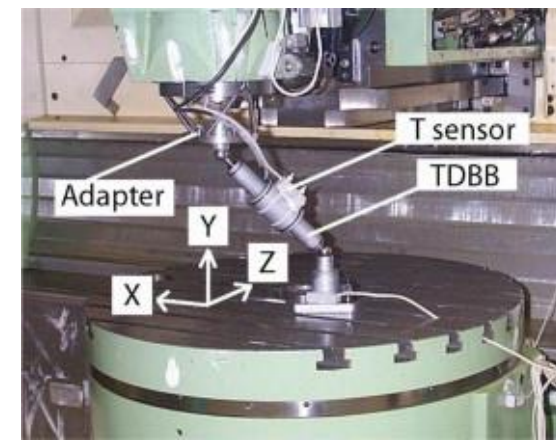


Kishawy *et al.* (2018) *Int J Adv Manuf Technol* **93** (5–8) 2275–2287

# Temperature measurement

## Machine tools

## Material removal process



Mayr J et al. (2012) *CIRP Annals* 61 771-791

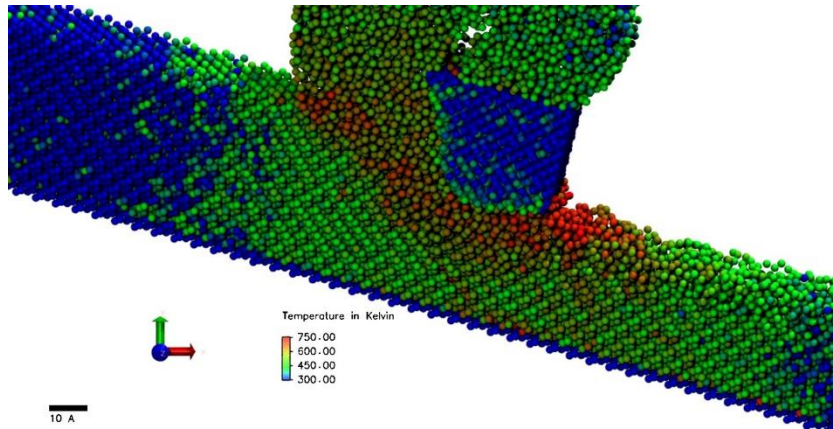
	RTD	Thermo-couple	Dynamic Thermo-couple	Single-Color Pyrometer	Two-Color Pyrometer	Thermo-physical
Temperature Range	Metal Melting	0°C-3000°C	Work Melting	20°C-5000°C+	0°C-5000°C+	$T_{trans}$
Spatial Resolution	500 $\mu\text{m}$	>500 $\mu\text{m}$ *10 $\mu\text{m}$	Interface Average	5 $\mu\text{m}$ (T dependent)	20 $\mu\text{m}$	100 $\mu\text{m}$
Time Resolution	2 ms	100 ms	-	ms to $\mu\text{s}$	ms to $\mu\text{s}$	Poor
Ease of set up	Easy	Easy	Easy	Difficult	Difficult	Easy-Medium
Dominant Uncertainty	Material Damage	Junctions	Junction Control	Emissivity	Gray Body Assumption	
Cost	Low-Medium	Low	Low	Medium-High	Medium	Low

Davis MA et al. (2007) *CIRP Annals* 57 581-604

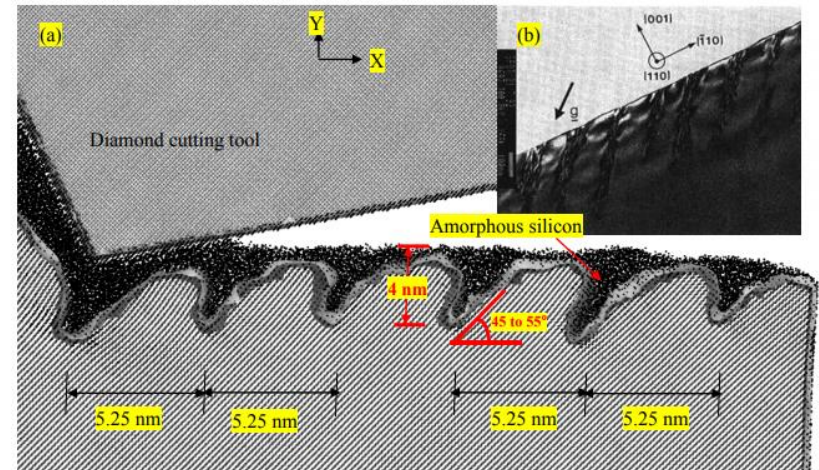


# Simulations results – Can we measure it?

## Point of contact

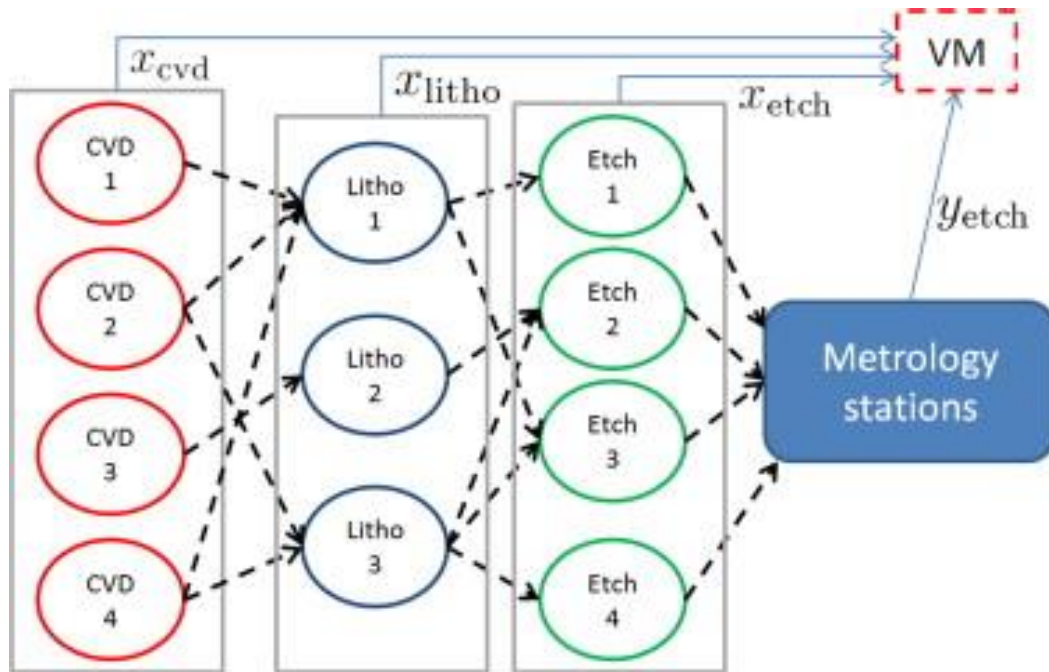


Goel S *et al.* (2012) *Wear* **284-285** 65-72



Goel S *et al.* (2016) *Acta Mat* **105** 464-478

Reduce the cost of metrology at the end point.



Susto et al (2015) *Comp Op Res* 53 328-337



# Conclusions

## Must have:

- Low cost
- Wide dynamic range
- Fast
- Cooperative
- Include non-dimensional (Temperature, Stress, Strain, Acoustic Emission, Force etc)
- Able to measure at the point of machining





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